

FP048R-VB Datasheet N-Channel 60 V (D-S) MOSFET

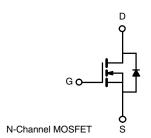
PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.007			
I _D (A)	150			
Configuration	Single			
Package	TO-247			

FEATURES

- Trench power MOSFET
- Package with low thermal resistance
- 100 % R_g and UIS tested







ABSOLUTE MAXIMUM RATIN	GS ($T_C = 25 ^{\circ}C$, unles	s otherwise noted)		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V _{DS}	60	V		
Gate-Source Voltage	V _{GS}	± 20	V		
Continuous Drain Current	T _C = 25 °C	1	150		
	T _C = 125 °C	- I _D	88		
Continuous Source Current (Diode Conduc	I _S	120	Α		
Pulsed Drain Current ^b	I _{DM}	480			
Single Pulse Avalanche Current	. 0.411	I _{AS}	65		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	211	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	Ъ	175	W	
	T _C = 125 °C	P_{D}	56	VV	
Operating Junction and Storage Temperature Range		T _J , T _{sta}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	40	°C/W		
Junction-to-Case (Drain)		R_{thJC}	0.88	G/VV		

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.

服务热线:400-655-8788

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SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0$, $I_D = 250 \mu A$		60	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		3.0	3.5]	
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 60 V, T _J = 125 °C	-	-	50	μA	
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 175 °C	-	-	250	1	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	V _{DS} ≥ 5 V	120	-	-	Α	
		V _{GS} = 10 V	I _D = 30 A	-	0.007	-	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	0.010	-		
		V _{GS} = 10 V	I _D = 30 A, T _J = 175 °C	-	0.013	-		
Forward Transconductance b	9 _{fs}	V_{DS}	= 15 V, I _D = 30 A	-	94	-	S	
Dynamic ^b		•						
Input Capacitance	C _{iss}			-	5196	-		
Output Capacitance	Coss	$V_{GS} = 0 V$	V _{DS} = 25 V, f = 1 MHz	-	710	-	рF	
Reverse Transfer Capacitance	C _{rss}			-	340	-]	
Total Gate Charge ^c	Qg			-	97	-		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_D = 75 \text{ A}$	5 A -	24.6	-	nC	
Gate-Drain Charge ^c	Q _{gd}			-	27.2	-		
Gate Resistance	R_g	f = 1 MHz		0.3	1	1.7	Ω	
Turn-On Delay Time ^c	t _{d(on)}				16	24		
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V, } R_L = 0.4 \Omega$ $I_D \cong 75 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 1 \Omega$		-	14	21	ns ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	34	51		
Fall Time ^c	t _f			-	9	14]	
Source-Drain Diode Ratings and Characteristics ^b								
Pulsed Current ^a	I _{SM}			-	-	480	Α	
Forward Voltage	V _{SD}	$I_F = 75 \text{ A}, V_{GS} = 0$		-	0.9	1.5	V	

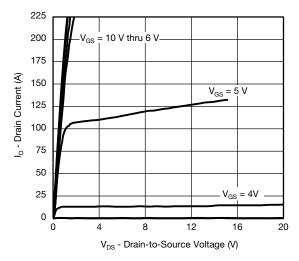
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

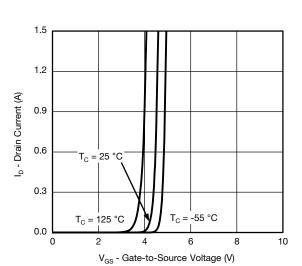
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



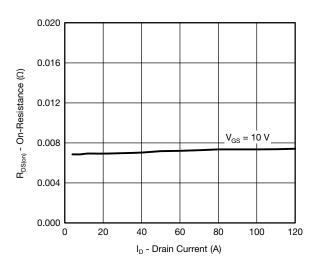
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



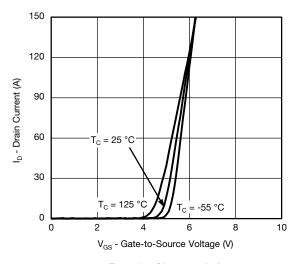




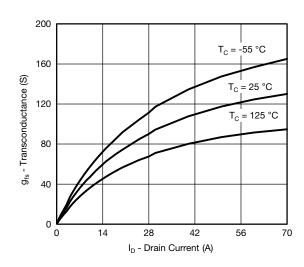
Transfer Characteristics



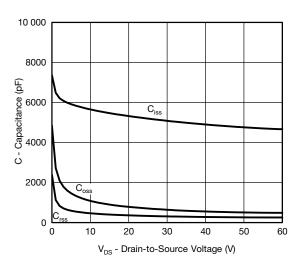
On-Resistance vs. Drain Current



Transfer Characteristics



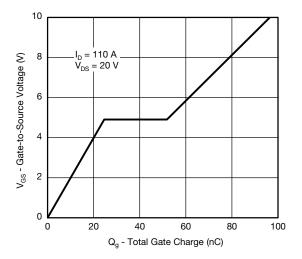
Transconductance



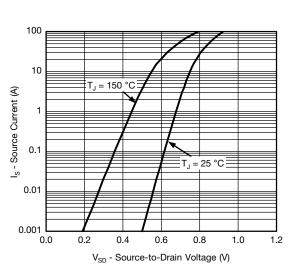
Capacitance



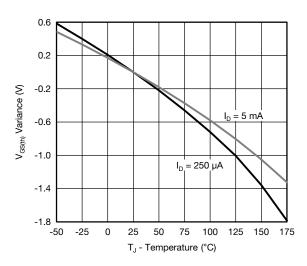
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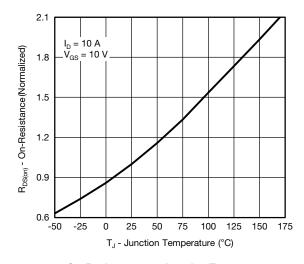
Gate Charge



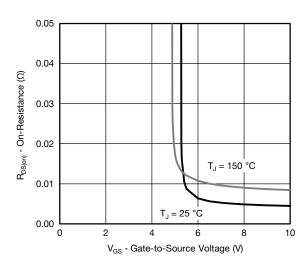
Source Drain Diode Forward Voltage



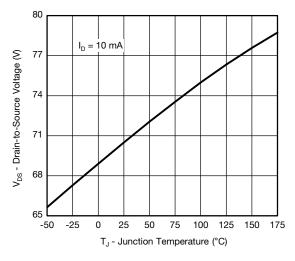
Threshold Voltage



On-Resistance vs. Junction Temperature



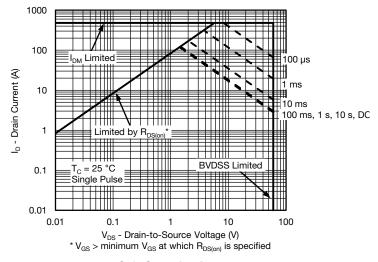
On-Resistance vs. Gate-to-Source Voltage



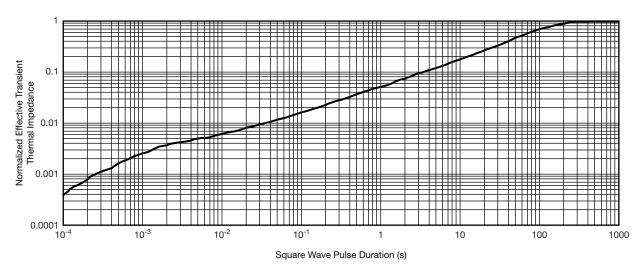
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



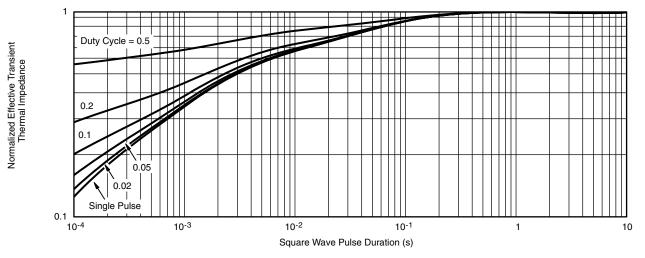
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



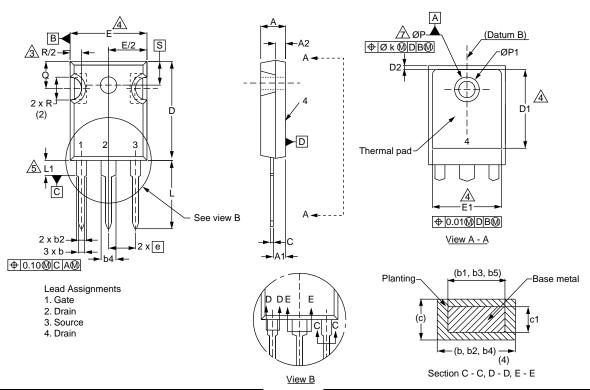
Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-247AC



	MILLIM	IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.58	5.31	0.180	0.209
A1	2.21	2.59	0.087	0.102
A2	1.17	2.49	0.046	0.098
b	0.99	1.40	0.039	0.055
b1	0.99	1.35	0.039	0.053
b2	1.53	2.39	0.060	0.094
b3	1.65	2.37	0.065	0.093
b4	2.42	3.43	0.095	0.135
b5	2.59	3.38	0.102	0.133
С	0.38	0.86	0.015	0.034
c1	0.38	0.76	0.015	0.030
D	19.71	20.82	0.776	0.820
D1	13.08	-	0.515	=

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
D2	0.51	1.30	0.020	0.051
E	15.29	15.87	0.602	0.625
E1	13.72	-	0.540	-
е	5.46 BSC		0.215	BSC
Øk	0.254		0.010	
L	14.20	16.25	0.559	0.640
L1	3.71	4.29	0.146	0.169
N	7.62 BSC		0.300	BSC
ØΡ	3.51	3.66	0.138	0.144
Ø P1	-	7.39	-	0.291
Q	5.31	5.69	0.209	0.224
R	4.52	5.49	0.178	0.216
S	5.51 BSC		0.217	BSC



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